

In re application of

: Confirmation No. 6855

Akihisa HONGO et al.

Docket No. 2001-1846

Serial No. 10/017,384

Group Art Unit 1742

Filed December 18, 2001

Examiner Donald R. Valentine

SUBSTRATE PLATING METHOD AND APPARATUS

RECEIVED

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AMENDMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In response to the Office Action of September 3, 2003, the period for response to which having been extended by three months to March 3, 2004, kindly amend the above-referenced U.S. patent application as follows:

03/03/2004 BABRAHA1 00000094 10017384

02 FC:1201

86.00 OP